O03 Tm.06ttky D 79.8T

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Recurrent Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM,}$ V_{RWM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average forward rectified current	$I_{F(AV)}$	10	A
Non Repetitive Peak Surge Current	I_{FSM}	80	A
Thermal Resistance Junction to Case	$R\ _{Jc}$	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

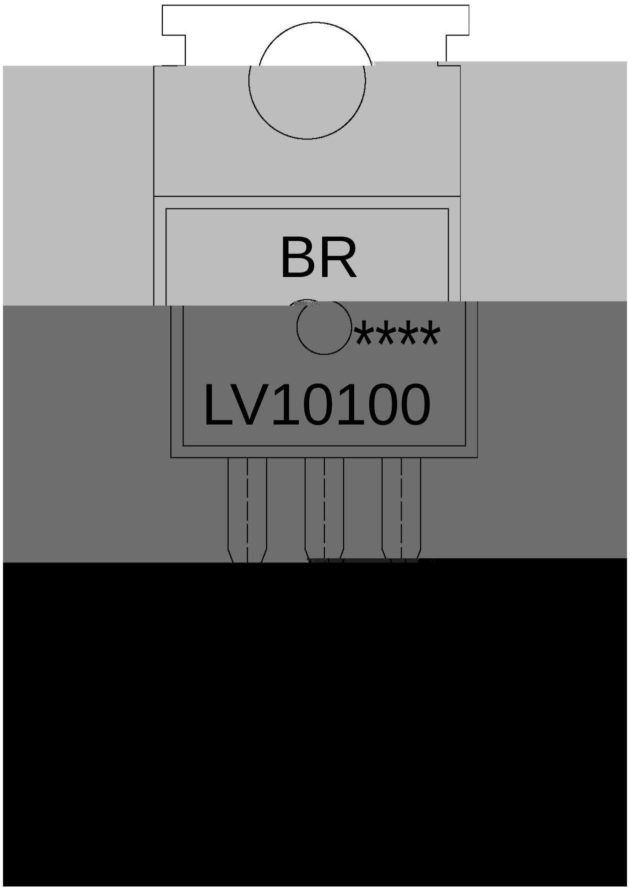
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Reverse Voltage	V_{BR}	I_R=100uA(Ta=25)	100			V
Forward Voltage	V_F	I_F =1A(Ta=25)		0.41	0.48	V
		I_F =3A(Ta=25)		0.48	0.53	V
		I_F =1A(Ta=125)			0.44	V
		I_F =3A(Ta=125)			0.50	V
Instantaneous Reverse Current	I_R Note 1	V_R=100V(Ta=25)		10	50	A
		V_R=100V(Ta=125)			10	mA

/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

/ Marking Instructions



Note:

BR:	Company Code
LV10100	Product Type.
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)

Note:

1 25 150 60 90sec;

2 255 5 5 0.5sec;

3 2 10 /sec.

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255 5 , Duration:5 0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec.

Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units		Dimension (unit mm^3)
	Units/Bag /	Bags/Inner Box /	